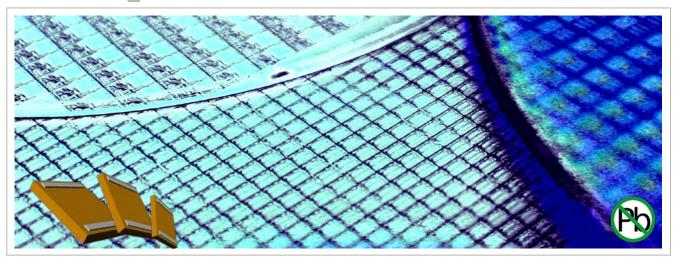


XTSC424.xxx - 0402 Extreme Temperature Silicon Capacitor

Rev 3.0



Key features

- Ultra High temperature up to 250°C:
 - Temperature Coeff : <±1.5%(-55 °C to +250°C)
 - Voltage <0.1 %/V
 - Negligible capacitance loss through aging
- Unique high capacitance in EIA/0402 package size, up to 47 nF
- High reliability (FIT <0.017 parts / billion hours)</p>
- Low leakage current < 100 pA</p>
- Low ESL and Low ESR
- Suitable for lead free reflow-soldering

Thanks to the unique IPDiA Silicon capacitor technology, most of the problems encountered in demanding applications can be solved.

EXtreme Temperature Silicon Capacitors are appropriate for applications used in extreme operating temperature range (up to **250°C**).

XTSC industry leading performances allows to propose a **47nF** in **0402** with a **TC<±1.5%** over the full -55°C/+250°C temperature range.

This technology also offers a **negligible ageing** and a stable insulation resistance, even at very high temperature, as well as a stable capacitor value over the full operating.

Key applications

- 250°C requirements, High temperature applications, such as military, aerospace, automotive and downhole industries.
- High reliability applications
- Replacement of X8R and COG dielectrics
- Decoupling / Filtering / Charge pump (i.e.: pressure sensor, motor management)
- Downsizing

The IPDiA technology features a capacitor integration capability (up to 250nF/mm²) which allows a capacitance value similar to X8R dielectric, but with better electrical performances than COG/NPO dielectrics.

This technology also offers **high reliability**, up to 10 times better than alternative capacitor technologies, such as Tantalum or MLCC, and eliminates cracking phenomena.

This Silicon based technology is RoHS compliant and compatible with lead free reflow soldering process.





Electrical specification

		Capacitance value						
		10	15	22	33	47	68	
	1 pF	Contact IPDIA Sales						
	10 pF	100 pF: 935.133.424.310	150 pF: 935.133.424.315	220 pF: 935.133.424.322	330 pF: 935.133.424.333	470 pF: 935.133.424.347	680 pF: 935.133.424.368	
Unit	0.1 nF	1 nF: 935.133.424.410	1.5 nF: 935.133.424.415	2.2 nF: 935.133.424.422	3.3 nF: 935.133.424.433	4.7 nF: 935.133.424.447	6.8 nF: 935.133.424.468	
	1 nF	10 nF: 935.133.424.510	15 nF: 935.133.424.515	22 nF: 935.133.424.522	33 nF: 935.133.424.533	47 nF: 935.133.424.547		
	10 nF							

^(*) Thinner thickness (as low as 100 µm thick) available, see Low Profile Silicon Capacitor product: LPSC

<u>Parameters</u>	<u>Value</u>	
Capacitance range	100pF to 47 nF ^(**)	
Capacitance tolerances	±15 % ^(**)	
Operating temperature range	-55 °C to 250 °C	
Storage temperatures	- 70 °C to 265 °C	
Temperature coefficient	<±1.5 %, from -55 °C to +250 °C	
Breakdown voltage (BV)	11 VDC, 30VDC ^(**)	
Capacitance variation versus RVDC	0.1 % /V (from 0 V to RVDC)	
Equivalent Serial Inductor (ESL)	Max 100 pH	
Equivalent Serial Resistor (ESR)	$Max 400mΩ^{(**)}$	
Insulation resistance	100GΩ min @ RVDC,25°C 50GΩ min @ RVDC,250°C	
Ageing	Negligible, < 0.001 % / 1000 h	
Reliability	FIT<0.017 parts / billion hours,	
Capacitor height	Max 400 μm ^(*)	

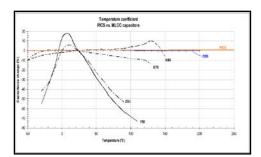


Fig.1 Capacitance change versus temperature variation compared with alternative dielectrics

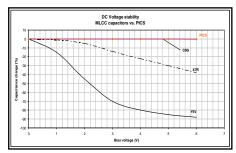


Fig.2 Capacitance change versus voltage variation compared with alternative dielectrics

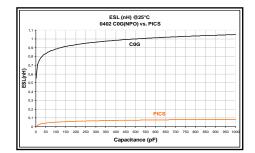


Fig.3 ESL versus capacitance value compared with alternative dielectrics

How to order



Termination and Outline

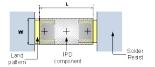
Termination

Lead-free nickel/solder coating compatible with automatic soldering technologies: reflow and manual

Typical dimensions, all dimensions in mm

Package outline

Тур.		0402
Comp.	П	1.20±0.05
size	W	0.70±0.05



(0402 PCB footprint)

Packaging

Tape and reel, tray, waffle pack or wafer delivery

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^(**) Other values on request